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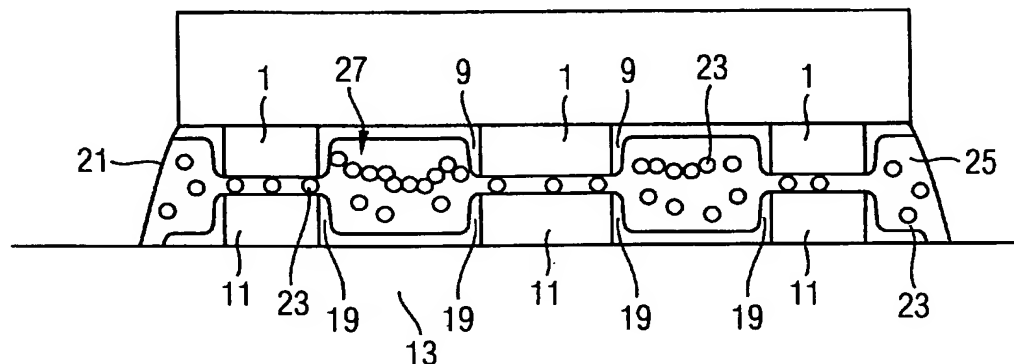
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(54) Title: ATTACHMENT OF FLIP-CHIPS TO SUBSTRATES



(57) Abstract: In a method of attaching a flip chip 3 to a substrate 13, insulating layers 9, 19 are formed on the lateral sides of the electrical contacts 1 of the flip chip 3 and the lateral sides of the electrical contacts 11 of the substrate 13. The flip-chip 3 is joined to the substrate 13 by a matrix 21 of insulating material 25 including electrically conductive particles 23. The insulating layers 9, 19 reduce the risk of the formation of horizontal conducting paths between the electrical contacts 1, 11.